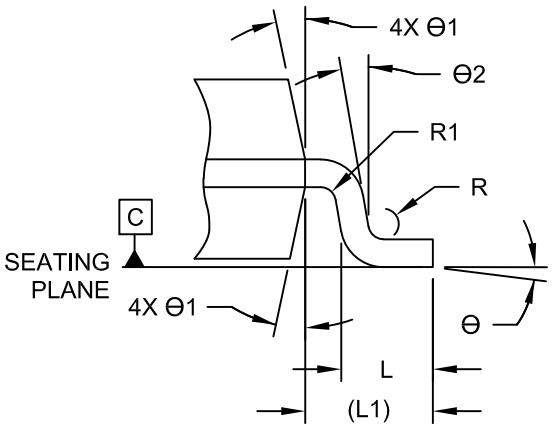
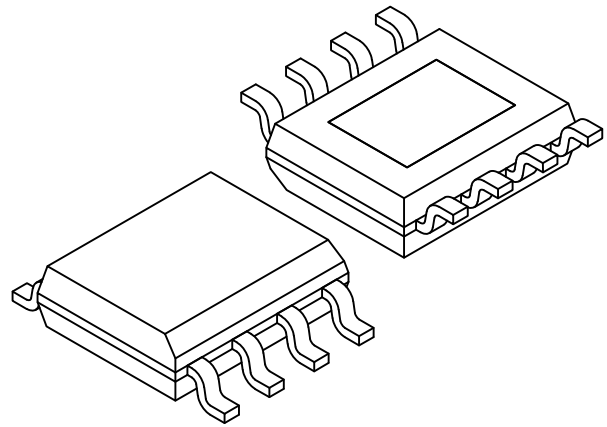
8-Lead Thermally Enhanced Plastic Small Outline (S7X) - Narrow, 3.90 mm Body [SOIC] With 2.2 x 3.0 mm Exposed Pad

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



SECTION A-A



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		8	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	1.75
Molded Package Thickness	A2	1.25	-	-
Standoff §	A1	0.00	-	0.15
Overall Width	E		6.00 BSC	
Molded Package Width	E1		3.90 BSC	
Overall Length	D		4.90 BSC	
Exposed Pad Width	E2	2.05	2.23	2.41
Exposed Pad Length	D1	2.81	3.06	3.30
Chamfer (Optional)	h	0.25	-	0.50
Foot Length	L	0.40	-	1.27
Footprint	L1		1.04 REF	
Lead Thickness	c	0.17	-	0.25
Lead Width	b	0.31	-	0.51
Lead Bend Radius	R	0.07	-	-
Lead Bend Radius	R1	0.07	-	-
Foot Angle	Θ	0°	-	8°
Lead Angle	Θ2	0°	-	-
Mold Draft Angle Top and Bottom	Θ1	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.